

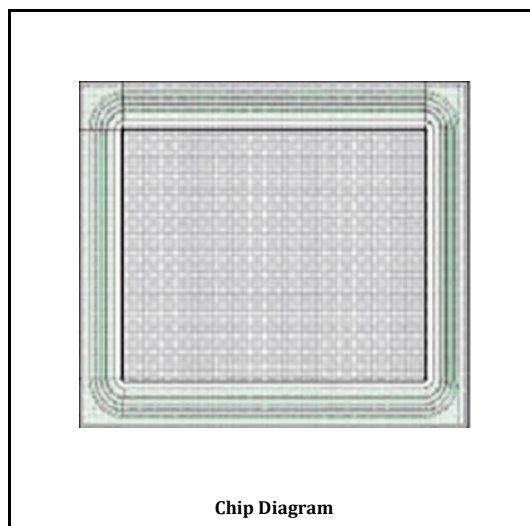
PRODUCT FEATURES

- ◆Ultrafast Recovery Time
- ◆Soft Recovery Characteristics
- ◆Low Forward Voltage
- ◆Low Leakage Current
- ◆Low Recovery Loss

Applications (not limited to)

- ◆Freewheeling, Snubber, Clamp
- ◆Snubber Diode
- ◆Switch Power Supplies
- ◆Motor control
- ◆Inverters, Converters

Items	Description
Wafer Size	5 Inch
Gross Die	230 EA
Top Metal	Al/Ag
Back Metal	Ag
Dimensions	um
Chip Size	6600μm * 6600μm
Pad Size	5800μm * 5800μm
Wafer Thickness	260±20μm
Scribe Line width	100 μm
Bonding Wire In case Top Metal=Al	Al, 18mil*3



Absolute Maximum ratings (T_a=25℃)

Parameter	Symbol	Value	Units
DC Blocking Voltage	V _{RRM}	400	V
Average Rectified Forward Current	I _{FAV}	75	A
Nonrepetitive Peak Surge Current@8.3ms	I _{FSM}	750	A
Operating Junction Temperature	T _J	175	℃
Storage Temperature	T _{STG}	- 55~150	℃

Electrical specification (T_a=25℃)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Breakdown Voltage	V _{BR}	I _R =50μA	400	470	-	V
Forward Voltage	V _F	I _F =75A, T _a =25℃	-	1.15	1.35	V
		I _F =75A, T _a =125℃	-	1.00	1.25	V
Reverse Leakage Current	I _R	V _R =400V, T _a =25℃	-	-	10	μA
		V _R =400V, T _a =125℃	-	-	200	μA
Reverse Recovery Time	T _{rr}	I _F =0.5A, I _R =1A, I _{rr} =0.25A	-	55	70	ns
		I _F =1A, V _R =30V, di/dt=-200A/us	-	45	-	ns

Remark:

- 1.Customer should obtain the latest version of datasheet before placing order, and verify the relevant information.
- 2.Cutting damage and chipping area can't beyond scribe line in given size range.
- 3.Testing system of T_{rr} could be different, customer might take secondary test to evaluate if necessary.
- 4.Customer might choose the bonding wire material and diameter according to actual situation, while no less than our recommendation.